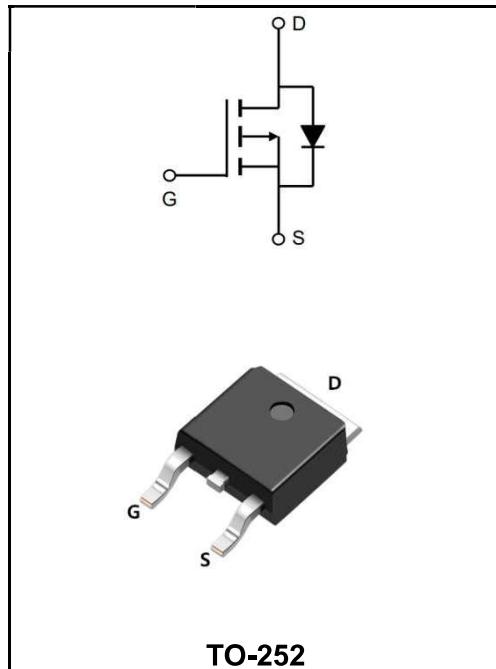


**-30V P-CHANNEL ENHANCEMENT MODE MOSFET**
**MAIN CHARACTERISTICS**

$I_D$	-60A
$V_{DSS}$	-30V
$R_{DS(on)-typ}(@V_{GS}=-10V)$	< 13mΩ (Type: 9 mΩ)


**Application**

- ◆ Lithium battery protection
- ◆ Wireless impact
- ◆ Mobile phone fast charging

**Product Specification Classification**

Part Number	Package	Marking	Pack
YFW60P03AD	TO-252	YFW 60P03AD XXXXX	2500PCS/Tape

**Maximum Ratings at  $T_c=25^\circ\text{C}$  unless otherwise specified**

Characteristics	Symbols	Value	Units
Drain-Source Voltage	$V_{DS}$	-30	V
Gate - Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current, $V_{GS} @ -10V^1$ @ $T_c=25^\circ\text{C}$	$I_D$	-60	A
Continuous Drain Current, $V_{GS} @ -10V^1$ @ $T_c=100^\circ\text{C}$	$I_D$	-30	A
Pulsed Drain Current <sup>2</sup>	$I_{DM}$	-150	A
Single Pulse Avalanche Energy <sup>3</sup>	$E_{AS}$	125	mJ
Avalanche Current	$I_{AS}$	-50	A
Total Power Dissipation <sup>4</sup> @ $T_c=25^\circ\text{C}$	$P_D$	45	W
Storage Temperature Range	$T_{STG}$	-55 to +150	°C
Operating Junction Temperature Range	$T_J$	-55 to +150	°C
Thermal Resistance Junction-Ambient <sup>1</sup>	$R_{\theta JA}$	62	°C/W
Thermal Resistance Junction to Case <sup>1</sup>	$R_{\theta JC}$	2.8	°C/W

**Maximum Ratings at Tc=25°C unless otherwise specified**

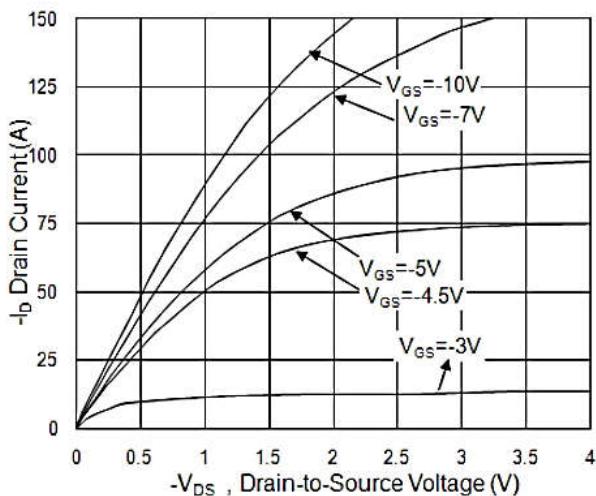
Characteristics	Test Condition	Symbols	Min	Typ	Max	Units
Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =-250uA	BV <sub>DSS</sub>	-30	-32	-	V
BV <sub>DSS</sub> Temperature Coefficient	Reference to 25°C , I <sub>D</sub> =-1mA	ΔBV <sub>DSS/ΔTJ</sub>	-	-0.0232	-	V/°C
Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =-10V, I <sub>D</sub> =-30A	R <sub>DS(ON)</sub>	-	9.0	13	mΩ
	V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-15A		-	13	18	
Gate -Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =-250uA	V <sub>GS(th)</sub>	-1.2	-1.6	-2.5	V
V <sub>GS(th)</sub> Temperature Coefficient		ΔV <sub>GS(th)</sub>	-	4.6	-	mV/°C
Drain-Source Leakage Current	V <sub>DS</sub> =-24V , V <sub>GS</sub> =0V , T <sub>J</sub> =25°C	I <sub>DSS</sub>	-	-	-1	μA
	V <sub>DS</sub> =-24V , V <sub>GS</sub> =0V , T <sub>J</sub> =55°C		-	-	-5	
Gate –Source Leakage Current	V <sub>GS</sub> =±25V, V <sub>DS</sub> =0V	I <sub>GSS</sub>	-	-	±100	nA
Forward Transconductance	V <sub>DS</sub> =-5V , I <sub>D</sub> =-30A	g <sub>fs</sub>	-	30	-	S
Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz	R <sub>g</sub>	-	9	-	Ω
Total Gate Charge(-4.5V)	V <sub>DS</sub> =-15V V <sub>GS</sub> =-4.5V I <sub>D</sub> =-15A	Q <sub>g</sub>	-	22	-	nC
Gate-Source Charge		Q <sub>gs</sub>	-	8.7	-	
Gate-Drain Charge		Q <sub>gd</sub>	-	7.2	-	
Turn-on delay time	V <sub>DD</sub> =-15V V <sub>GS</sub> =-10V I <sub>D</sub> =-15A R <sub>G</sub> =3.3Ω	t <sub>d(on)</sub>	-	8	-	ns
Rise Time		T <sub>r</sub>	-	73.7	-	
Turn-Off Delay Time		t <sub>d(OFF)</sub>	-	61.8	-	
Fall Time		t <sub>f</sub>	-	24.4	-	
Input Capacitance	V <sub>DS</sub> =-15V V <sub>GS</sub> =0V f=1MHz	C <sub>iss</sub>	-	2215	-	pF
Output Capacitance		C <sub>oss</sub>	-	310	-	
Reverse Transfer Capacitance		C <sub>rss</sub>	-	237	-	
Continuous Source Current <sup>1,5</sup>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current	I <sub>s</sub>	-	-	-45	A
Pulsed Source Current <sup>2,5</sup>		I <sub>SM</sub>	-	-	-150	A
Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>s</sub> =-1A , T <sub>J</sub> =25°C	V <sub>SD</sub>	-	-	-1	V
Reverse Recovery Time	I <sub>F</sub> =-15A, dI/dt=100A/μs, T <sub>J</sub> =25°C	t <sub>rr</sub>	-	19	-	ns
Reverse Recovery Charge		Q <sub>rr</sub>	-	9	-	nC

Note :

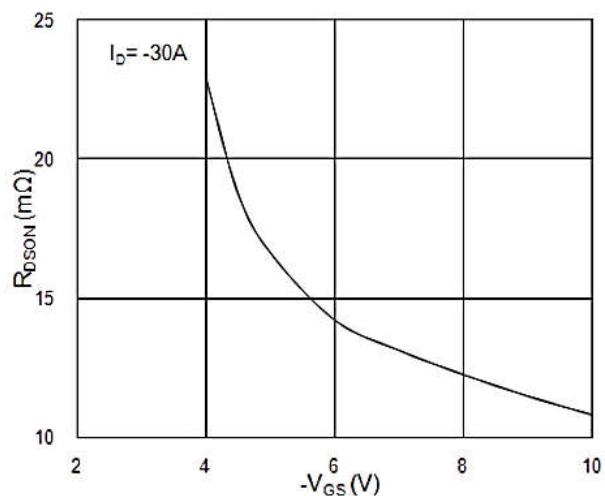
1. The data tested by surface mounted on a 1 inch 2 FR-4 board with 2OZ copper.
2. The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
3. The EAS data shows Max. rating . The test condition is VDD=-25V,VGS=-10V,L=0.1mH,IAS=-50A
4. The power dissipation is limited by 150°C junction temperature
5. The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.

**Ratings and Characteristic Curves**

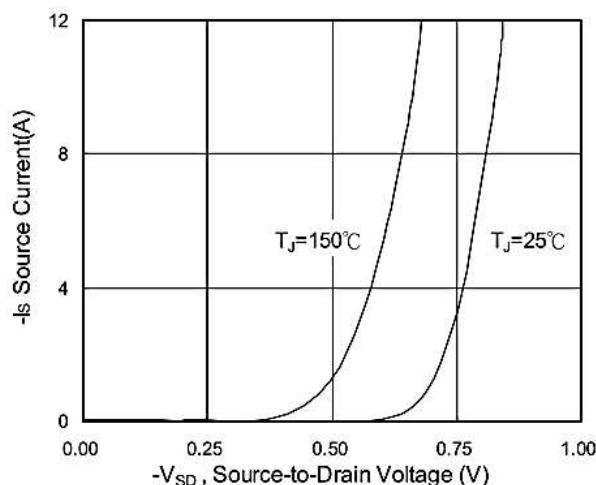
**Typical Characteristics**



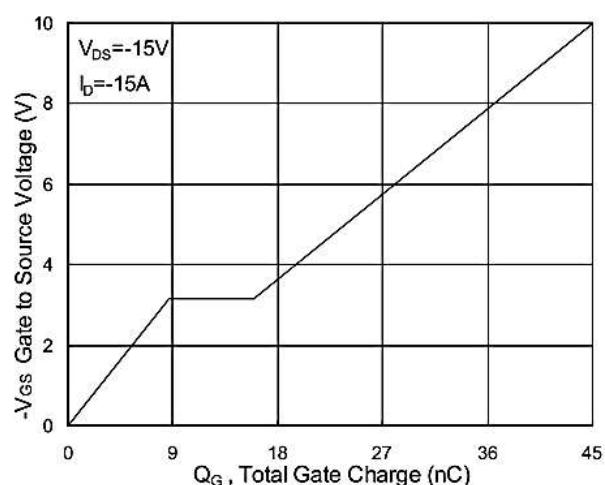
**Fig.1 Typical Output Characteristics**



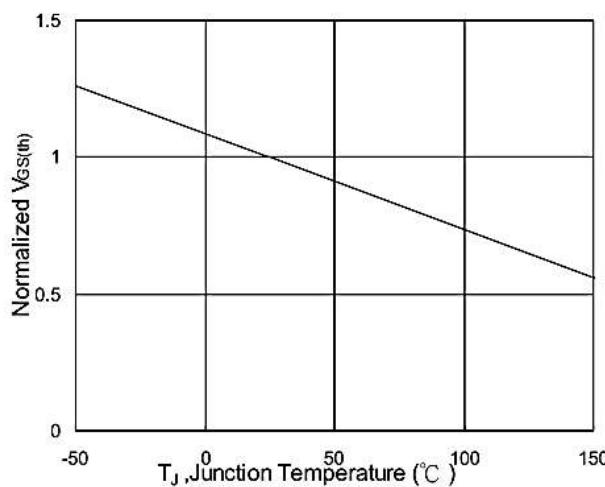
**Fig.2 On-Resistance vs. G-S Voltage**



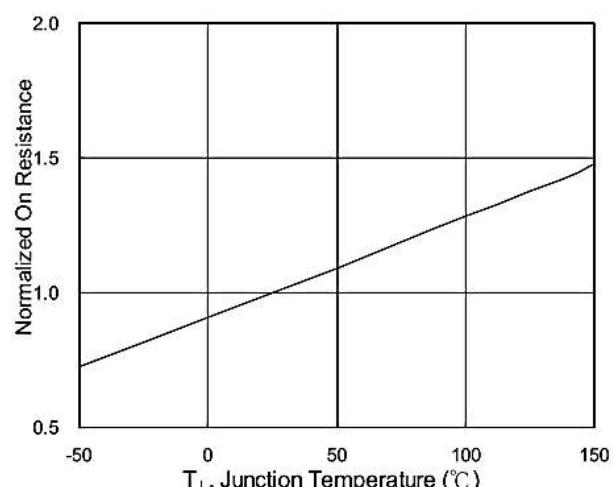
**Fig.3 Forward Characteristics of Reverse**



**Fig.4 Gate-charge Characteristics**



**Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$**



**Fig.6 Normalized  $R_{DS(on)}$  vs.  $T_J$**

**Ratings and Characteristic Curves**

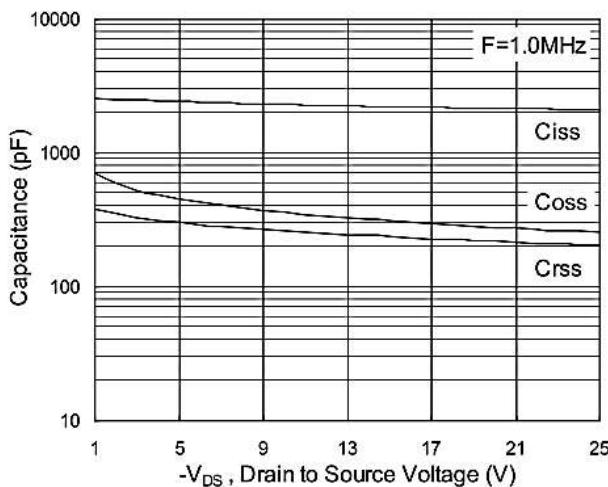


Fig.7 Capacitance

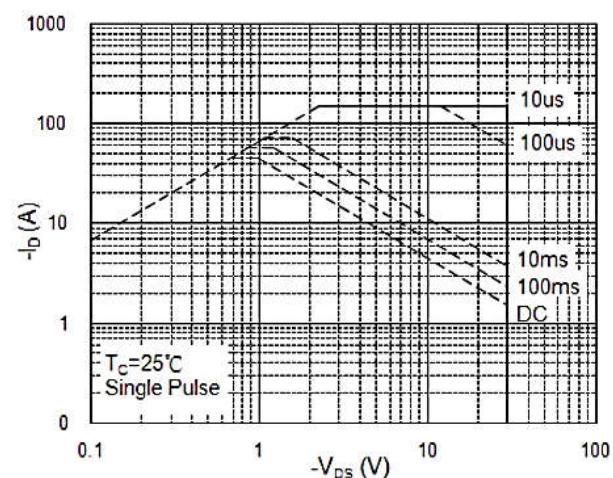


Fig.8 Safe Operating Area

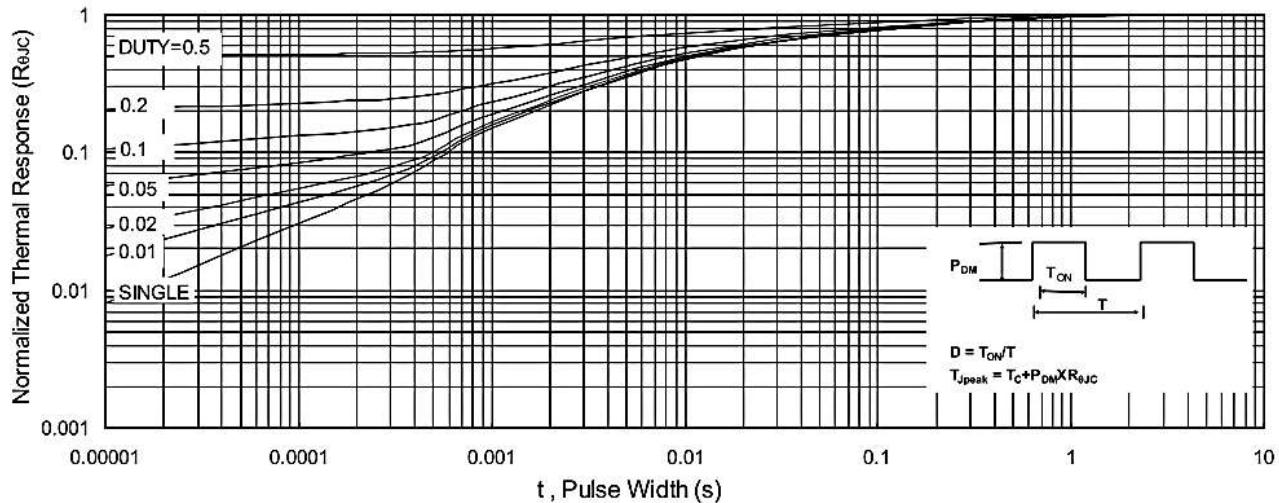


Fig.9 Normalized Maximum Transient Thermal Impedance

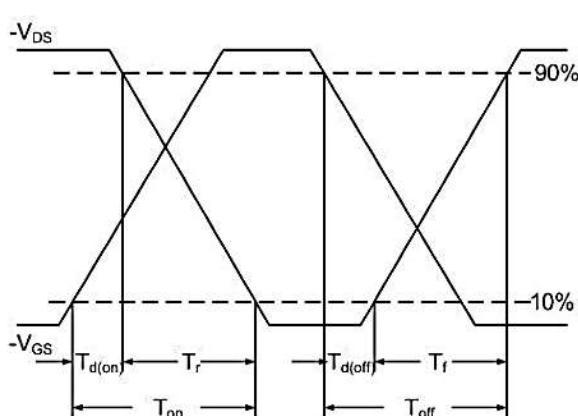


Fig.10 Switching Time Waveform

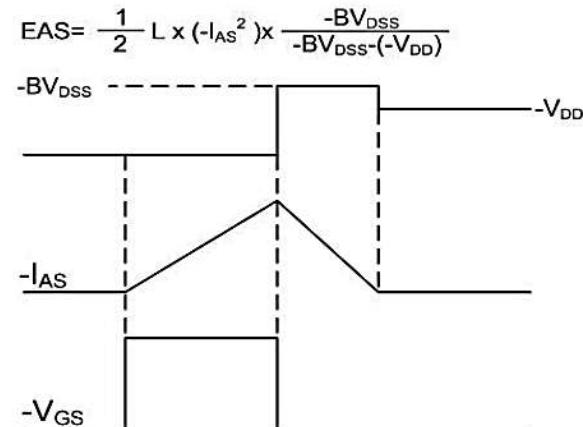
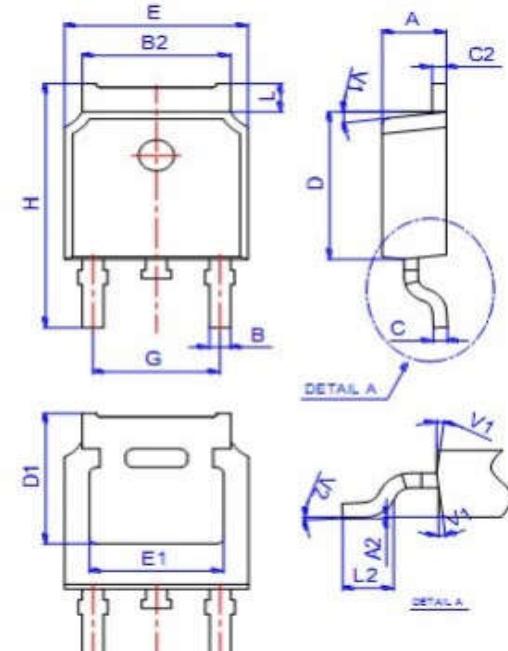


Fig.11 Unclamped Inductive Switching Waveform

**Package Outline Dimensions Millimeters**

**TO-252**



Dim.	Min.	Typ.	Max.
A	2.10	-	2.50
A2	0	-	0.10
B	0.66	-	0.86
B2	5.18	-	5.48
C	0.40	-	0.60
C2	0.44	-	0.58
D	5.90	-	6.30
D1	5.30REF		
E	6.40	-	6.80
E1	4.63	-	-
G	4.47	-	4.67
H	9.50	-	10.70
L	1.09	-	1.21
L2	1.35	-	1.65
V1	-	7°	-
V2	0°	-	6°

All Dimensions in millimeter